

**IN THE SPECIFICATION**

Please amend the application as follows:

Please add the following paragraph at page 1, after the title:

This application is a continuation of U.S. Patent Application Serial No. 09/733,476, filed December 8, 2000, which is incorporated herein by reference.

**Please amend the paragraph at page 3, line 20 as follows:**

Figure 2 shows a top view of one embodiment of a pressure plate 200. In one embodiment, the pressure plate 200 is a dish-shaped elastically deformable plate that has an apex (also referred to as a summit) 202 and a periphery 204. The pressure plate 200 may be deformed by applying a force 206 at the periphery 204, resulting in a force generally directed towards the apex 202. The force 206 is preferentially directed towards the apex 202 to avoid warping the circuit board 104.

**PRELIMINARY AMENDMENT**

Serial Number: Unknown

Filing Date: Herewith

Title: I/C PACKAGE/THERMAL-SOLUTION RETENTION MECHANISM WITH SPRING EFFECT

Assignee: Intel Corporation

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Dkt: 884.355US2 (INTEL)

Conclusion

The Examiner is invited to telephone Applicant's Attorney to facilitate prosecution of this application.

Respectfully Submitted,

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